

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	(glass adj transition) and temperature and (photoresist adj film) and semiconductor and flow and pattern and ARC and (critical adj dimension) and (contact adj hole)	USPAT	OR	OFF	2005/03/30 12:52
L4	841	(438/710).CCLS.	USPAT	OR	OFF	2005/03/30 12:45
L5	463	(438/626).CCLS.	USPAT	OR	OFF	2005/03/30 12:52
S1	41584	(glass adj transition)	USPAT	OR	OFF	2004/12/01 16:38
S2	5	(glass adj transition) and temperature and photoresist and semiconductor and micropattern	USPAT	OR	OFF	2004/12/01 16:38
S3	0	(glass adj transition) and temperature and photoresist and semiconductor and micropattern and RFP	USPAT	OR	OFF	2004/12/01 16:42
S4	1	(glass adj transition) and temperature and photoresist and semiconductor and (resist adj flow adj pattern)	USPAT	OR	OFF	2004/12/01 16:42
S5	0	(glass adj transition) and temperature and photoresist and semiconductor and RFP	USPAT	OR	OFF	2004/12/01 16:43
S6	398	(glass adj transition) and temperature and photoresist and semiconductor and flow and pattern and film	USPAT	OR	OFF	2004/12/01 16:43
S7	72	(glass adj transition) and temperature and (photoresist adj film) and semiconductor and flow and pattern	USPAT	OR	OFF	2004/12/01 16:43
S8	0	(glass adj transition) and temperature and (photoresist adj film) and semiconductor and flow and pattern and (anti-reflection)	USPAT	OR	OFF	2004/12/01 16:43
S9	9	(glass adj transition) and temperature and (photoresist adj film) and semiconductor and flow and pattern and ARC	USPAT	OR	OFF	2005/03/30 12:45
S10	1	(glass adj transition) and temperature and (photoresist adj film) and semiconductor and flow and pattern and ARC and (critical adj dimension)	USPAT	OR	OFF	2005/03/30 12:31